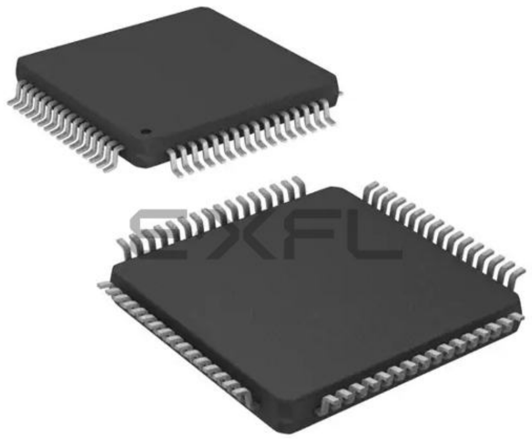

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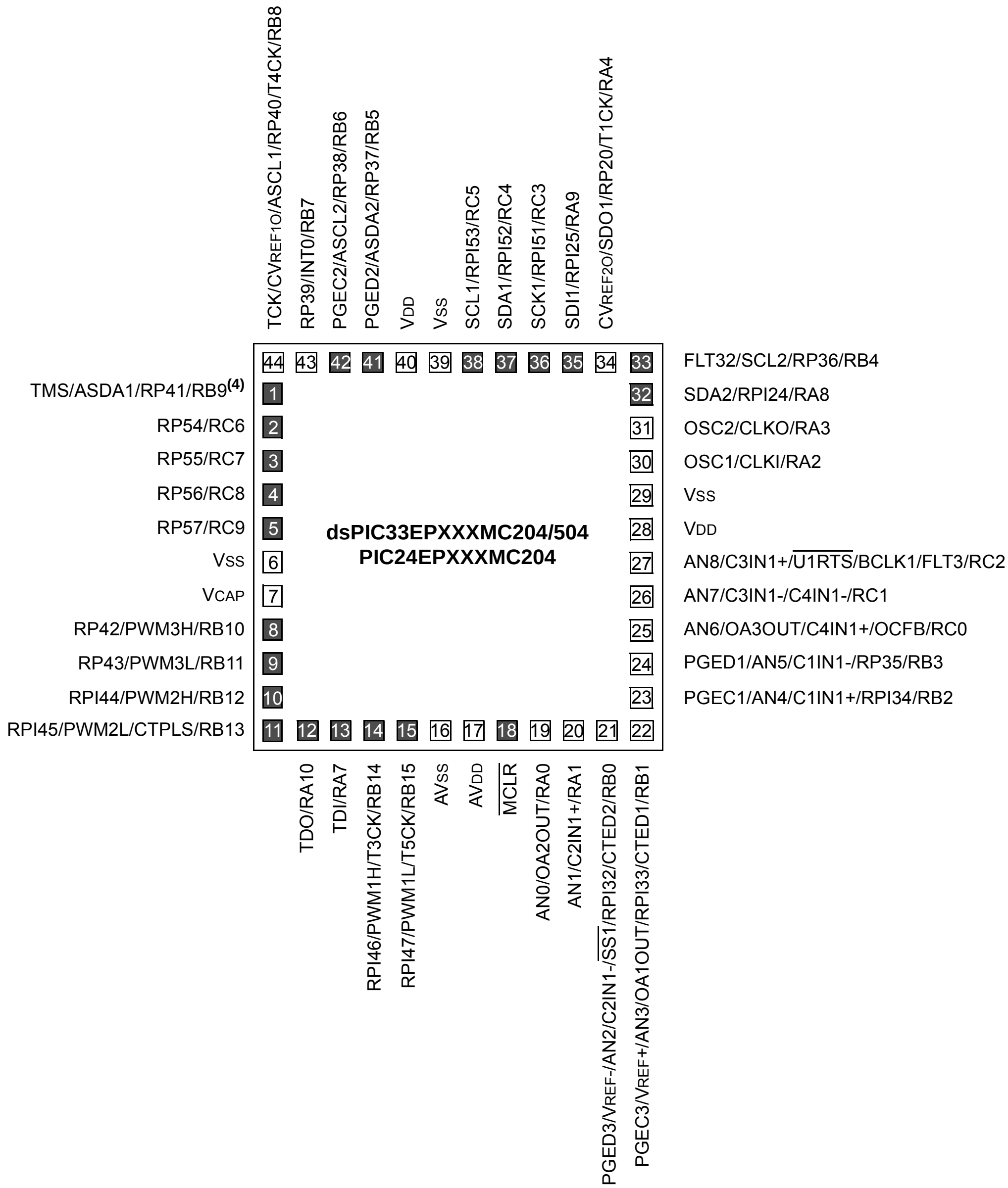
Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc206-h-pt

Pin Diagrams (Continued)

44-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



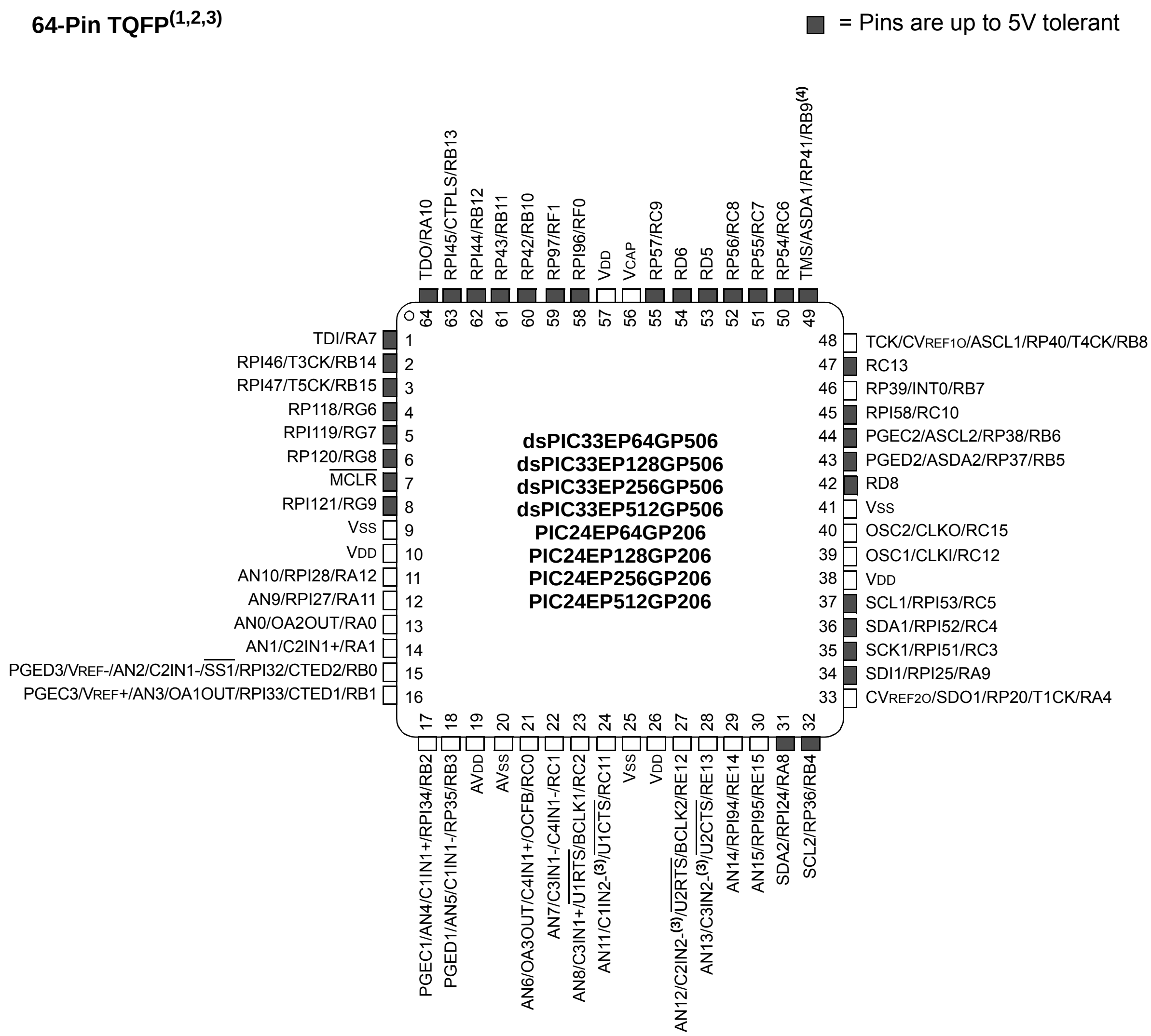
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

Pin Diagrams (Continued)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

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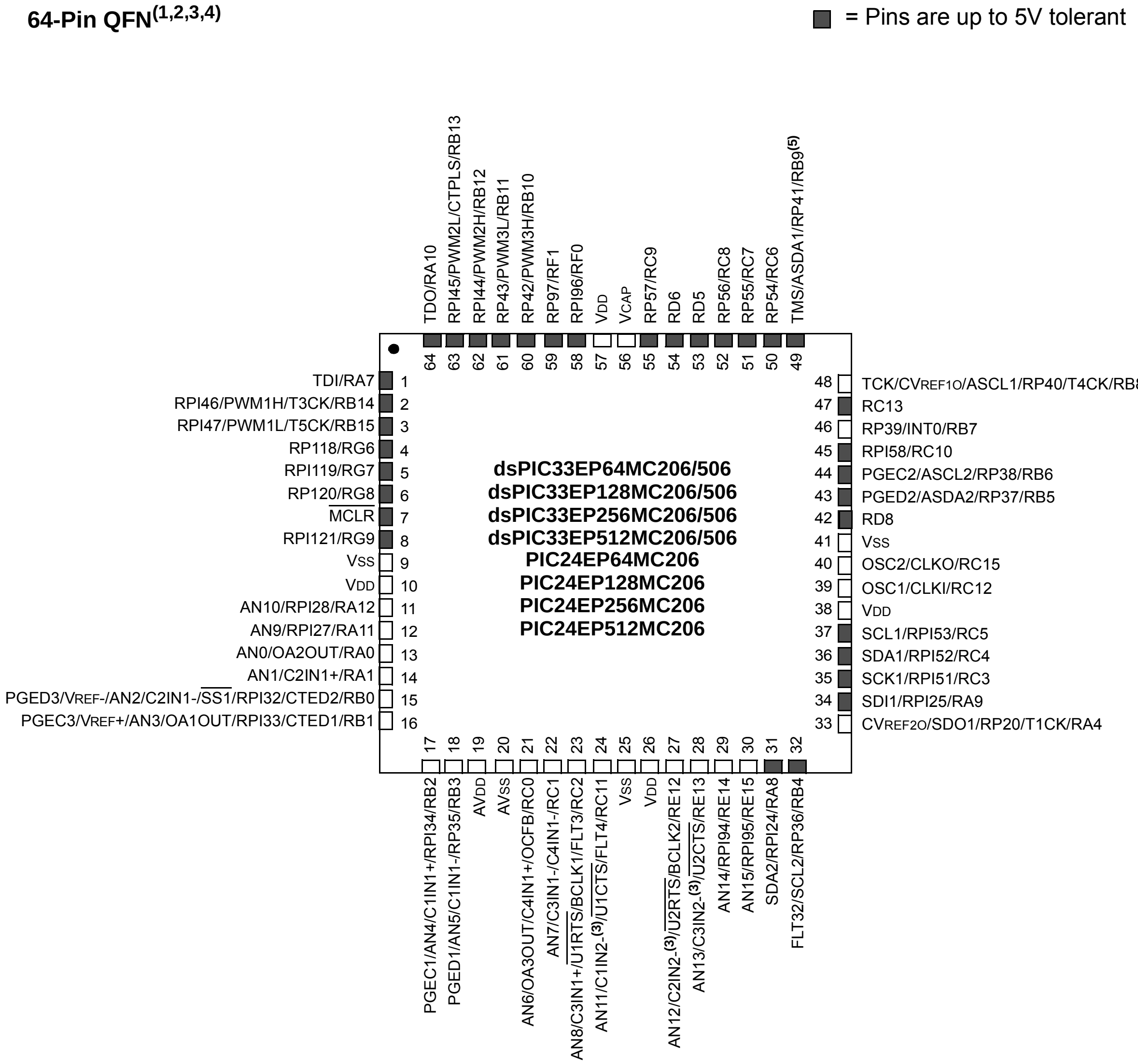
Pin Diagrams (Continued)

64-Pin QFN(1,2,3,4)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

TABLE 4-53: PORTA REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISA	0E00	—	—	—	—	—	TRISA10	TRISA9	TRISA8	TRISA7	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	079F
PORTA	0E02	—	—	—	—	—	RA10	RA9	RA8	RA7	—	—	RA4	RA3	RA2	RA1	RA0	0000
LATA	0E04	—	—	—	—	—	LATA10	LATA9	LATA8	LATA7	—	—	LATA4	LATA3	LATA2	LA1TA1	LA0TA0	0000
ODCA	0E06	—	—	—	—	—	ODCA10	ODCA9	ODCA8	ODCA7	—	—	ODCA4	ODCA3	ODCA2	ODCA1	ODCA0	0000
CNENA	0E08	—	—	—	—	—	CNIEA10	CNIEA9	CNIEA8	CNIEA7	—	—	CNIEA4	CNIEA3	CNIEA2	CNIEA1	CNIEA0	0000
CNPUA	0E0A	—	—	—	—	—	CNPUA10	CNPUA9	CNPUA8	CNPUA7	—	—	CNPUA4	CNPUA3	CNPUA2	CNPUA1	CNPUA0	0000
CNPDA	0E0C	—	—	—	—	—	CNPDA10	CNPDA9	CNPDA8	CNPDA7	—	—	CNPDA4	CNPDA3	CNPDA2	CNPDA1	CNPDA0	0000
ANSELA	0E0E	—	—	—	—	—	—	—	—	—	—	—	ANSA4	—	—	ANSA1	ANSA0	0013

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-54: PORTB REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISB	0E10	TRISB15	TRISB14	TRISB13	TRISB12	TRISB11	TRISB10	TRISB9	TRISB8	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
PORTB	0E12	RB15	RB14	RB13	RB12	RB11	RB10	RB9	RB8	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
LATB	0E14	LATB15	LATB14	LATB13	LATB12	LATB11	LATB10	LATB9	LATB8	LATB7	LATB6	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
ODCB	0E16	ODCB15	ODCB14	ODCB13	ODCB12	ODCB11	ODCB10	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
CNENB	0E18	CNIEB15	CNIEB14	CNIEB13	CNIEB12	CNIEB11	CNIEB10	CNIEB9	CNIEB8	CNIEB7	CNIEB6	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
CNPUB	0E1A	CNPUB15	CNPUB14	CNPUB13	CNPUB12	CNPUB11	CNPUB10	CNPUB9	CNPUB8	CNPUB7	CNPUB6	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
CNPDB	0E1C	CNPDB15	CNPDB14	CNPDB13	CNPDB12	CNPDB11	CNPDB10	CNPDB9	CNPDB8	CNPDB7	CNPDB6	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
ANSELB	0E1E	—	—	—	—	—	—	—	ANSB8	—	—	—	—	ANSB3	ANSB2	ANSB1	ANSB0	010F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-55: PORTC REGISTER MAP FOR PIC24EPXXXGP/MC204 AND dsPIC33EPXXXGP/MC204/504 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TRISC	0E20	—	—	—	—	—	—	TRISC9	TRISC8	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	03FF
PORTC	0E22	—	—	—	—	—	—	RC9	RC8	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx
LATC	0E24	—	—	—	—	—	—	LATC9	LATC8	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	xxxx
ODCC	0E26	—	—	—	—	—	—	ODCC9	ODCC8	ODCC7	ODCC6	ODCC5	ODCC4	ODCC3	ODCC2	ODCC1	ODCC0	0000
CNENC	0E28	—	—	—	—	—	—	CNIEC9	CNIEC8	CNIEC7	CNIEC6	CNIEC5	CNIEC4	CNIEC3	CNIEC2	CNIEC1	CNIEC0	0000
CNPUC	0E2A	—	—	—	—	—	—	CNPUC9	CNPUC8	CNPUC7	CNPUC6	CNPUC5	CNPUC4	CNPUC3	CNPUC2	CNPUC1	CNPUC0	0000
CNPDC	0E2C	—	—	—	—	—	—	CNPDC9	CNPDC8	CNPDC7	CNPDC6	CNPDC5	CNPDC4	CNPDC3	CNPDC2	CNPDC1	CNPDC0	0000
ANSELC	0E2E	—	—	—	—	—	—	—	—	—	—	—	—	—	ANSC2	ANSC1	ANSC0	0007

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read, and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages, by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address prior to modification addresses an EDS or PSV page
- The EA calculation uses Pre-Modified or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-61 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-61: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS and PSV SPACE BOUNDARIES(2,3,4)

O/U, R/W	Operation	Before			After		
		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description
O, Read	`[++Wn]` or `[Wn++]`	DSRPAG = 0x1FF	1	EDS: Last page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	`[--Wn]` or `[Wn--]`	DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo-Linear Addressing is not supported for large offsets.

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4.8 Interfacing Program and Data Memory Spaces

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture uses a 24-bit-wide Program Space (PS) and a 16-bit-wide Data Space (DS). The architecture is also a modified Harvard scheme, meaning that data can also be present in the Program Space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the architecture of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provides two methods by which Program Space can be accessed during operation:

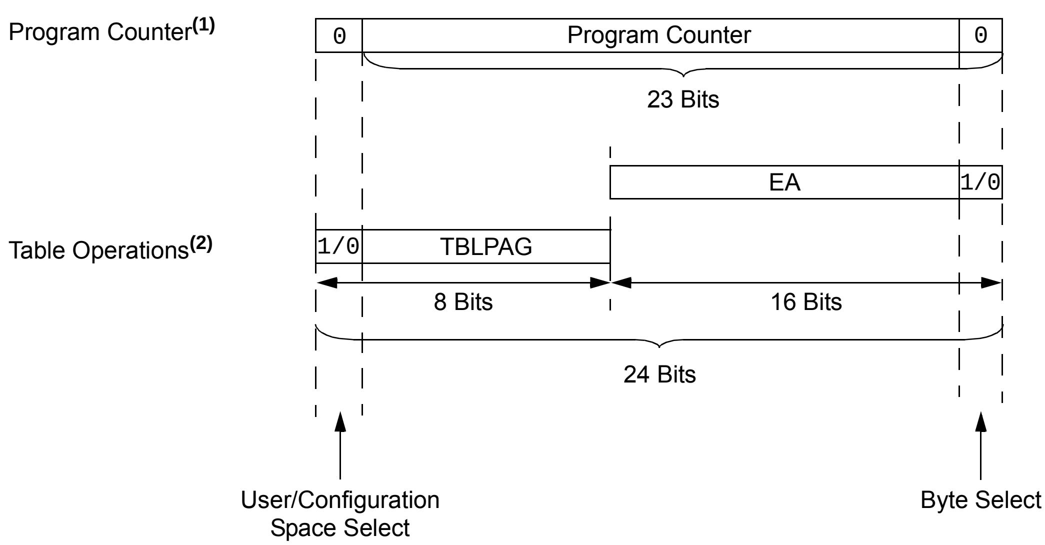
- Using table instructions to access individual bytes or words anywhere in the Program Space
- Remapping a portion of the Program Space into the Data Space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look-ups from a large table of static data. The application can only access the least significant word of the program word.

TABLE 4-65: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		

FIGURE 4-22: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The Least Significant bit (LSb) of Program Space addresses is always fixed as '0' to maintain word alignment of data in the Program and Data Spaces.

2: Table operations are not required to be word-aligned. Table Read operations are permitted in the configuration memory space.

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than V_{DD} by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum V_{IH} specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum V_{IH} specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (V_{OH} or V_{OL}) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a `NOP`, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV   0xFF00, W0   ; Configure PORTB<15:8>
                   ; as inputs
MOV   W0, TRISB    ; and PORTB<7:0>
                   ; as outputs
NOP                ; Delay 1 cycle
BTSS  PORTB, #13   ; Next Instruction
```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REGISTER 11-24: RPOR6: PERIPHERAL PIN SELECT OUTPUT REGISTER 6

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP57R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP56R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP57R<5:0>:** Peripheral Output Function is Assigned to RP57 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP56R<5:0>:** Peripheral Output Function is Assigned to RP56 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-25: RPOR7: PERIPHERAL PIN SELECT OUTPUT REGISTER 7

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP97R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP97R<5:0>:** Peripheral Output Function is Assigned to RP97 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-0 **Unimplemented:** Read as ‘0’

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REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER

HS/HC-0	HS/HC-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLTSTAT[(1)]	CLSTAT[(1)]	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB[(2)]	MDCS[(2)]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DTC1	DTC0	DTCP[(3)]	—	MTBS	CAM[(2,4)]	XPRES[(5)]	IUE[(2)]
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FLTSTAT:** Fault Interrupt Status bit[(1)]
1 = Fault interrupt is pending
0 = No Fault interrupt is pending
This bit is cleared by setting FLTIEN = 0.

bit 14 **CLSTAT:** Current-Limit Interrupt Status bit[(1)]
1 = Current-limit interrupt is pending
0 = No current-limit interrupt is pending
This bit is cleared by setting CLIEN = 0.

bit 13 **TRGSTAT:** Trigger Interrupt Status bit
1 = Trigger interrupt is pending
0 = No trigger interrupt is pending
This bit is cleared by setting TRGIEN = 0.

bit 12 **FLTIEN:** Fault Interrupt Enable bit
1 = Fault interrupt is enabled
0 = Fault interrupt is disabled and the FLTSTAT bit is cleared

bit 11 **CLIEN:** Current-Limit Interrupt Enable bit
1 = Current-limit interrupt is enabled
0 = Current-limit interrupt is disabled and the CLSTAT bit is cleared

bit 10 **TRGIEN:** Trigger Interrupt Enable bit
1 = A trigger event generates an interrupt request
0 = Trigger event interrupts are disabled and the TRGSTAT bit is cleared

bit 9 **ITB:** Independent Time Base Mode bit[(2)]
1 = PHASEx register provides time base period for this PWM generator
0 = PTPER register provides timing for this PWM generator

bit 8 **MDCS:** Master Duty Cycle Register Select bit[(2)]
1 = MDC register provides duty cycle information for this PWM generator
0 = PDCx register provides duty cycle information for this PWM generator

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be ‘1’ and the CLMOD bit in the FCLCONx register must be ‘0’.

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18.3 SPIx Control Registers

REGISTER 18-1: SPIxSTAT: SPIx STATUS AND CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
SPIEN	—	SPISIDL	—	—	SPIBEC<2:0>		
bit 15							bit 8

R/W-0	R/C-0, HS	R/W-0	R/W-0	R/W-0	R/W-0	R-0, HS, HC	R-0, HS, HC
SRMPT	SPIROV	SRXMPT	SISEL2	SISEL1	SISEL0	SPITBF	SPIRBF
bit 7							bit 0

Legend:	C = Clearable bit	HS = Hardware Settable bit	HC = Hardware Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **SPIEN:** SPIx Enable bit
1 = Enables the module and configures SCKx, SDOx, SDIx and $\overline{\text{SSx}}$ as serial port pins
0 = Disables the module

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SPISIDL:** SPIx Stop in Idle Mode bit
1 = Discontinues the module operation when device enters Idle mode
0 = Continues the module operation in Idle mode

bit 12-11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPIBEC<2:0>:** SPIx Buffer Element Count bits (valid in Enhanced Buffer mode)
Master mode:
Number of SPIx transfers that are pending.
Slave mode:
Number of SPIx transfers that are unread.

bit 7 **SRMPT:** SPIx Shift Register (SPIxSR) Empty bit (valid in Enhanced Buffer mode)
1 = SPIx Shift register is empty and Ready-To-Send or receive the data
0 = SPIx Shift register is not empty

bit 6 **SPIROV:** SPIx Receive Overflow Flag bit
1 = A new byte/word is completely received and discarded; the user application has not read the previous data in the SPIxBUF register
0 = No overflow has occurred

bit 5 **SRXMPT:** SPIx Receive FIFO Empty bit (valid in Enhanced Buffer mode)
1 = RX FIFO is empty
0 = RX FIFO is not empty

bit 4-2 **SISEL<2:0>:** SPIx Buffer Interrupt Mode bits (valid in Enhanced Buffer mode)
111 = Interrupt when the SPIx transmit buffer is full (SPITBF bit is set)
110 = Interrupt when last bit is shifted into SPIxSR and as a result, the TX FIFO is empty
101 = Interrupt when the last bit is shifted out of SPIxSR and the transmit is complete
100 = Interrupt when one data is shifted into the SPIxSR and as a result, the TX FIFO has one open memory location
011 = Interrupt when the SPIx receive buffer is full (SPIRBF bit is set)
010 = Interrupt when the SPIx receive buffer is 3/4 or more full
001 = Interrupt when data is available in the receive buffer (SRMPT bit is set)
000 = Interrupt when the last data in the receive buffer is read and as a result, the buffer is empty (SRXMPT bit is set)

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REGISTER 22-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge Sampling Mode Selection bit
1 = Edge 1 is edge-sensitive
0 = Edge 1 is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1xxx = Reserved
01xx = Reserved
0011 = CTED1 pin
0010 = CTED2 pin
0001 = OC1 module
0000 = Timer1 module

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the edge source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the edge source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 7 **EDG2MOD:** Edge 2 Edge Sampling Mode Selection bit
1 = Edge 2 is edge-sensitive
0 = Edge 2 is level-sensitive

bit 6 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 is programmed for a positive edge response
0 = Edge 2 is programmed for a negative edge response

bit 5-2 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = Reserved
01xx = Reserved
0100 = CMP1 module
0011 = CTED2 pin
0010 = CTED1 pin
0001 = OC1 module
0000 = IC1 module

bit 1-0 **Unimplemented:** Read as '0'

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REGISTER 25-1: CMSTAT: OP AMP/COMPARATOR STATUS REGISTER (CONTINUED)

bit 1 **C2OUT:** Comparator 2 Output Status bit(2)

When CPOL = 0:
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$

When CPOL = 1:
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

bit 0 **C1OUT:** Comparator 1 Output Status bit(2)

When CPOL = 0:
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$

When CPOL = 1:
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

Note 1: Reflects the value of the of the CEVT bit in the respective Op Amp/Comparator Control register, CMxCON<9>.

2: Reflects the value of the COUT bit in the respective Op Amp/Comparator Control register, CMxCON<8>.

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CON	COE(2)	CPOL	—	—	OPMODE	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator Enable bit
1 = Op amp/comparator is enabled
0 = Op amp/comparator is disabled

bit 14 **COE:** Comparator Output Enable bit(2)
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as ‘0’

bit 10 **OPMODE:** Op Amp/Comparator Operation Mode Select bit
1 = Circuit operates as an op amp
0 = Circuit operates as a comparator

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to the EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN}+ > V_{IN}-$
0 = $V_{IN}+ < V_{IN}-$
When CPOL = 1 (inverted polarity):
1 = $V_{IN}+ < V_{IN}-$
0 = $V_{IN}+ > V_{IN}-$

Note 1: Inputs that are selected and not available will be tied to VSS. See the **“Pin Diagrams”** section for available inputs for each package.
2: This output is not available when OPMODE (CMxCON<10>) = 1.

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FIGURE 30-9: HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

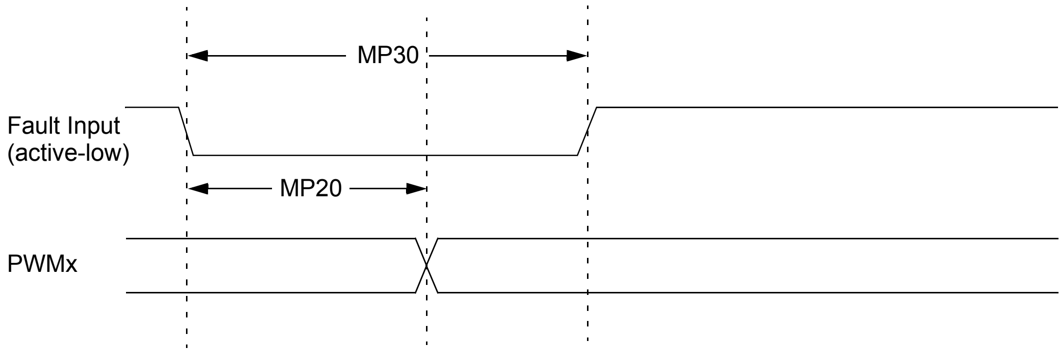
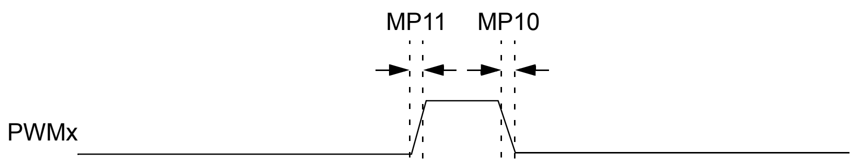


FIGURE 30-10: HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MP10	TFPWM	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	TRPWM	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	TFD	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	TFH	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

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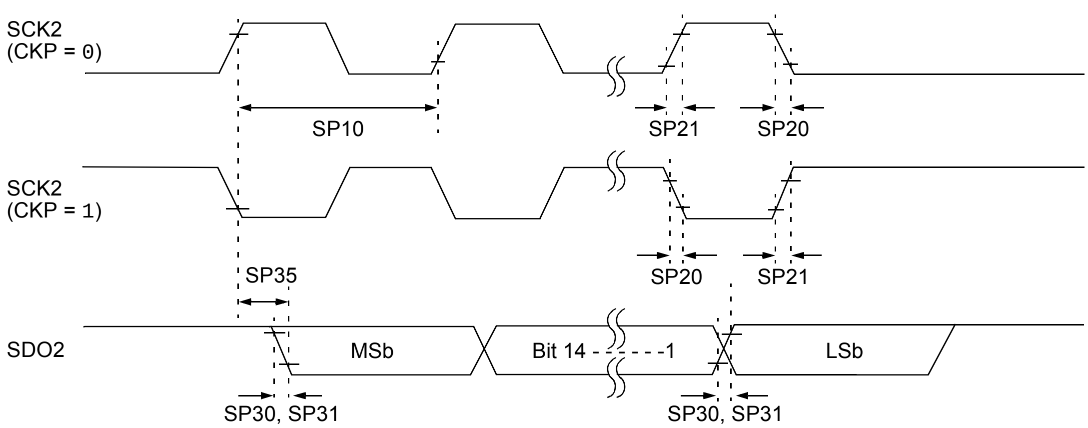
TABLE 30-33: SPI2 MAXIMUM DATA/CLOCK RATE SUMMARY

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-33	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-34	—	1	0,1	1
9 MHz	—	Table 30-35	—	0	0,1	1
15 MHz	—	—	Table 30-36	1	0	0
11 MHz	—	—	Table 30-37	1	1	0
15 MHz	—	—	Table 30-38	0	1	0
11 MHz	—	—	Table 30-39	0	0	0

FIGURE 30-14: SPI2 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

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TABLE 30-47: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.
3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.
4: Assumes 50 pF load on all SPI1 pins.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C		
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC60e	1400	2500	μA	+150°C	3.3V	Base Power-Down Current **(Notes 1, 3)**
HDC61c	15	—	μA	+150°C	3.3V	Watchdog Timer Current: ΔIWDT **(Notes 2, 4)**

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C		
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC44e	12	30	mA	+150°C	3.3V	40 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C		
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC20	9	15	mA	+150°C	3.3V	10 MIPS
HDC22	16	25	mA	+150°C	3.3V	20 MIPS
HDC23	30	50	mA	+150°C	3.3V	40 MIPS

TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS					**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C		
Parameter No.	**Typical**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	24	35	1:2	mA	+150°C	3.3V	40 MIPS
HDC72f(1)	14	—	1:64	mA			
HDC72g(1)	12	—	1:128	mA			

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.

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FIGURE 32-9: TYPICAL FRC FREQUENCY @ V_{DD} = 3.3V

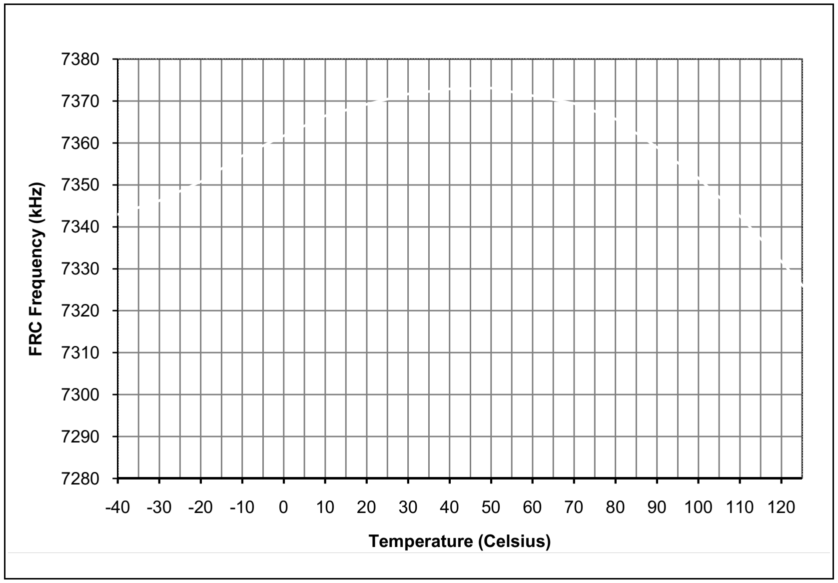


FIGURE 32-10: TYPICAL LPRC FREQUENCY @ V_{DD} = 3.3V

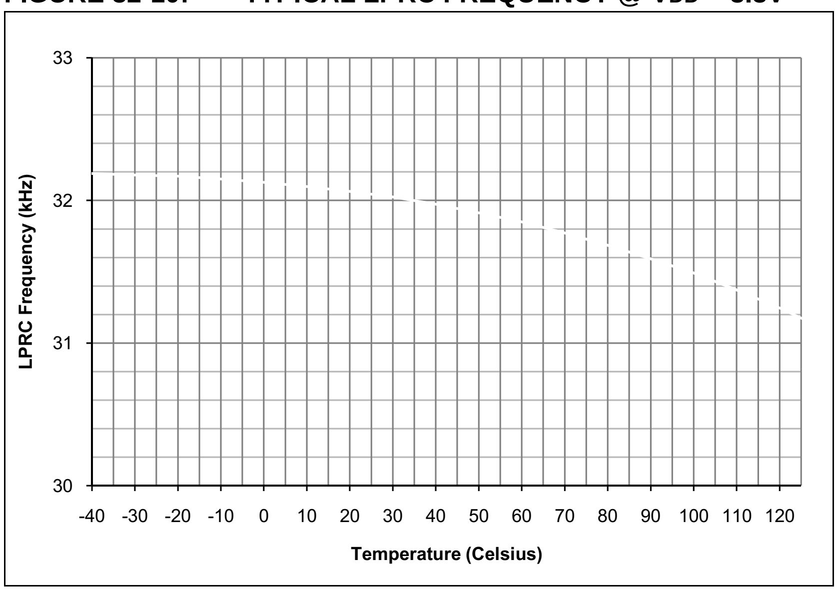
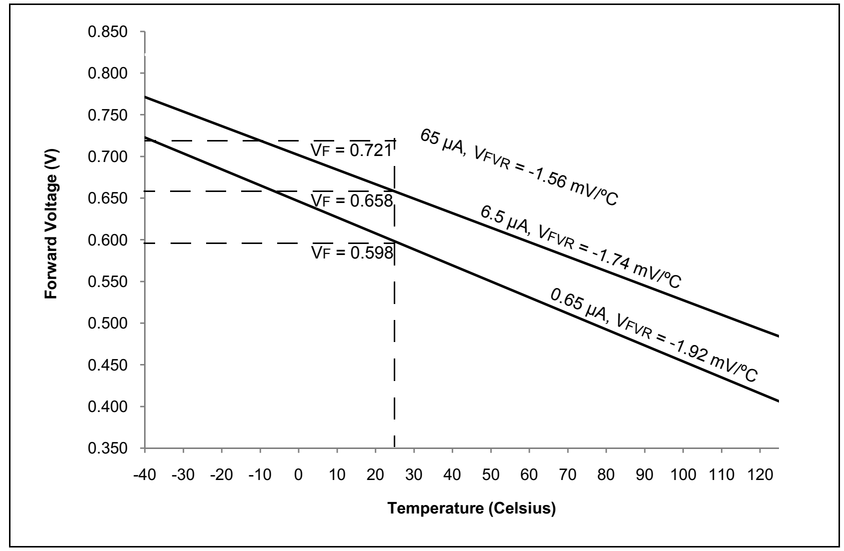


FIGURE 32-11: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



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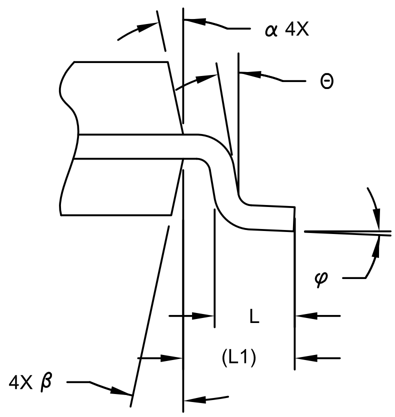
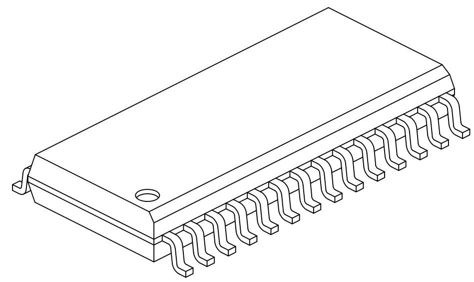
28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

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TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics" (Continued)	These SPI2 Timing Requirements were updated: • Maximum value for Parameter SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-36, Table 30-37, and Table 30-38) • Maximum value for Parameter SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-40 and Table 30-42) • The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-43) These SPI1 Timing Requirements were updated: • Maximum value for Parameters SP10 and the minimum clock period value for SCKx in Note 3 (see Table 30-44, Table 30-45, and Table 30-46) • Maximum value for Parameters SP70 and the minimum clock period value for SCKx in Note 3 (see Table 30-47 through Table 30-50) • Minimum value for Parameters SP40 and SP41 see Table 30-44 through Table 30-50) Updated all Typical values for the CTMU Current Source Specifications (see Table 30-55). Updated Note1, the Maximum value for Parameter AD06, the Minimum value for AD07, and the Typical values for AD09 in the ADC Module Specifications (see Table 30-56). Added Note 1 to the ADC Module Specifications (12-bit Mode) (see Table 30-57). Added Note 1 to the ADC Module Specifications (10-bit Mode) (see Table 30-58). Updated the Minimum and Maximum values for Parameter AD21b in the 10-bit Mode ADC Module Specifications (see Table 30-58). Updated Note 2 in the ADC Conversion (12-bit Mode) Timing Requirements (see Table 30-59). Updated Note 1 in the ADC Conversion (10-bit Mode) Timing Requirements (see Table 30-60).

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